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DESCRIPTION

BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE

Technical Field

[0001] The present invention relates to a bump forming apparatus for forming bumps onto a charge appearance type semiconductor substrate such as a piezoelectric substrate or the like which generate electric charge in accordance with a temperature change (that is, a charge appearance semiconductor substrate) a method carried out by the bump forming apparatus for removing charge of the charge appearance semiconductor substrate, a charge removing unit installed in the bump forming apparatus for charge appearance semiconductor substrates, and a charge appearance semiconductor substrate.

Background Art

[0002] Electronic components installed in devices, e.g., portable phones and the like have been made compact these days in association with a great miniaturization of the devices. There is a bump forming apparatus which forms bumps on electrode parts in circuit form parts formed on a semiconductor wafer without separating the circuit form

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